

TECHNICAL SPEC FOR Spin etcher

**System Model:
NexGeN MG21**

Wafer size: 8inch

Chamber count: 1

Chamber type: 4 vertically process levels, made of PP. Each level of the process chamber allocated to specific chemistry cabinet.

CDS: Yes, 3 chemistry cabinets

DIW Arm: DI/N2 module with DI-arm

N2 Arm: DI/N2 module with N2-arm

Load system: manual load ports

Swivel levers: load and unload swivel lever module

Chuck: Bernoulli chuck

Heater exchanger: one inlineheater per medium

Temperature: max allowed 180degC

Dry N2 Monitor:

Suck back system: installed

Pumps:

Suck back valve: type LVC23U

Wafer defect system:

Endpoint Detection System: NA

Ozone processing: ozon unit present

Robot: end effector double sided (flip option)

Thin-wafer handling:

Chemicals used: HF, HCL, HNO3, N2, DI

SECS: installed

Vintage:

Missing parts:

Defected parts:

Software: NexGen

Operating system: windows 7

Photos to Collect

- All 4 sides
 - Process console
 - Electronic console
 - Canister console
- Control panel
- Turntable
- Inside all cabinets (boards, electronics and chemicals)
- Serial plate
- Spare parts, manuals (if any)